

BC212 PNP General Purpose Amplifier

- This device is designed for general purpose amplifier application at collector currents to 300m.
- ٠ Sourced from process 68.



1. Collector 2. Base 3. Emitter

Absolute Maximum Ratings T_C=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CBO}	Collector-Base Voltage	60	V
V _{CEO}	Collector-Emitter Voltage	50	V
V _{EBO}	Emitter-Base Voltage	5	V
I _C	Collector Current (DC)	300	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 ~ 150	°C

* These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

1) These ratings are based on a maximum junction temperature of 150 degrees C.

2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics Ta=25°C unless otherwise noted

Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation	625	mW
	Derate above 25°C	5.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	°C/W

*Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06".

Electrical Characteristics T_C=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
BV _{CBO}	Collector-Base Voltage	I _C = 10μA	60			V
BV _{CEO}	Collector-Emitter Voltage	$I_{\rm C} = 2mA$	50			V
BV _{EBO}	Emitter-Base Voltage	I _E = 10μA	5			V
I _{EBO}	Emitter Cut-off Current	$V_{EB} = 4V$			15	nA
I _{CBO}	Collector Cut-off Current	$V_{CB} = 30V$			15	nA
h _{FE}	DC Current Gain	$V_{CE} = 5V, I_C = 10\mu A$ $V_{CE} = 5V, I_C = 2mA$	40 60			
V _{CE} (sat)	Collector-Emitter Saturation Voltage	$I_{\rm C} = 100 \text{ mA}, I_{\rm B} = 5 \text{ mA}$			0.6	V
V _{BE} (sat)	Base-Emitter Saturation Voltage	$I_{\rm C} = 100 \text{ mA}, I_{\rm B} = 5 \text{ mA}$			1.4	V
V _{BE} (on)	Base-Emitter On Voltage	$V_{CE} = 5V, I_C = 2mA$	0.6		0.72	V
C _{ob}	Output Capacitance	V _{CE} = 10V, f = 1MHz			6	pF

Notes:

These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.
These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.
These ratings are based on a maximum junction temperature of 150degrees C.

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